



National Standards Authority of Ireland

IRISH STANDARD

I.S. EN 61192-4:2003

ICS 31.190

**WORKMANSHIP REQUIREMENTS FOR
SOLDERED ELECTRONIC ASSEMBLIES
PART 4: TERMINAL ASSEMBLIES
(IEC 61192-4:2002)**

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EUROPEAN STANDARD

EN 61192-4

NORME EUROPÉENNE

EUROPÄISCHE NORM

March 2003

ICS 31.190

English version

Workmanship requirements for soldered electronic assemblies
Part 4: Terminal assemblies
(IEC 61192-4:2002)

Exigences relatives à la qualité
d'exécution des assemblages
électroniques brasés
Partie 4: Assemblage au moyen
de bornes
(CEI 61192-4:2002)

Anforderungen an die Ausführungsqualität
von Lötbaugruppen
Teil 4: Baugruppen mit Lötstützpunkten
(IEC 61192-4:2002)

This European Standard was approved by CENELEC on 2003-03-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Luxembourg, Malta, Netherlands, Norway, Portugal, Slovakia, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 91/335/FDIS, future edition 1 of IEC 61192-4, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61192-4 on 2003-03-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2003-12-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2006-03-01

This standard should be used in conjunction with the following parts of EN 61192, under the general title *Workmanship requirements for soldered electronic assemblies*:

Part 1: General

Part 2: Surface-mount assemblies

Part 4: Terminal assemblies

Annexes designated "normative" are part of the body of the standard.

In this standard, annex ZA is normative.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 61192-4:2002 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	- ¹⁾	Printed board design, manufacture and assembly - Terms and definitions	-	-
IEC 60749	1996	Semiconductor devices - Mechanical and climatic test methods	EN 60749	1999
A2	2001		A2	2001
IEC 61189-3	- ¹⁾	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 3: Test methods for interconnection structures (printed boards)	EN 61189-3	1997 ²⁾
IEC 61191-1	- ¹⁾	Printed board assemblies Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	1998 ²⁾
IEC 61191-4	- ¹⁾	Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	1998 ²⁾
IEC 61192-1	- ¹⁾	Workmanship requirements for soldered electronic assemblies Part 1: General	EN 61192-1	2003 ²⁾
IEC 61192-2	- ¹⁾	Part 2: Surface-mount assemblies	-	-
IEC 61192-3	- ¹⁾	Part 3: Through-hole mount assemblies	EN 61192-3	2003 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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**Exigences relatives à la qualité d'exécution
des assemblages électroniques brasés –**

**Partie 4:
Assemblage au moyen de bornes**

**Workmanship requirements for
soldered electronic assemblies –**

**Part 4:
Terminal assemblies**



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CEI/IEC 61192-4:2002

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